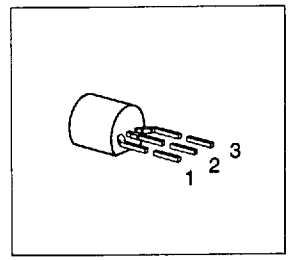
SIPMOS® Small-Signal Transistor

- V_{DS} 240 V
- I_D 0.15 A
- $R_{DS(on)}$ 20 Ω
- N channel
- Depletion mode
- High dynamic resistance
- Available grouped in $V_{GS(th)}$



Type	Ordering Code	Tape and Reel Information	Pin Configuration 1	2	3	Marking	Package
BSS 129	Q62702-S015	E6288: 1500 pcs/reel; 2 reels/carton; gate first	G	D	S	SS 129	TO-92
BSS 129	Q67000-S116	E6296: 1500 pcs/reel; 2 reels/carton; source first					

Maximum Ratings

Parameter	Symbol	Values	Unit
Drain-source voltage	V_{DS}	240	V
Drain-gate voltage, R_{GS} = 20 kΩ	V_{DGR}	240	
Gate-source voltage	V_{GS}	± 20	
ESD Sensitivity (HBM) as per MIL-STD 883	–	Class 1	
Continuous drain current, T_A = 37 °C	I_D	0.15	A
Pulsed drain current, T_A = 25 °C	$I_{D\,puls}$	0.45	
Max. power dissipation, T_A = 25 °C	P_{tot}	1.0	W
Operating and storage temperature range	T_j, T_{stg}	– 55 ... + 150	°C

Thermal resistance, chip-ambient (without heat sink)	R_{thJA}	≤ 125	K/W
DIN humidity category, DIN 40 040	–	E	–
IEC climatic category, DIN IEC 68-1	–	55/150/56	

Electrical Characteristics

at T_j = 25 °C, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage V_{GS} = – 3 V, I_D = 0.25 mA	$V_{(BR)DSS}$	240	–	–	V
Gate threshold voltage V_{DS} = 3 V, I_D = 1 mA	$V_{GS(th)}$	– 1.8	– 1.2	– 0.7	
Drain-source cutoff current V_{DS} = 240 V, V_{GS} = – 3 V T_j = 25 °C T_j = 125 °C	I_{DSS}	 – –	 – –	 100 200	 nA µA
Gate-source leakage current V_{GS} = 20 V, V_{DS} = 0	I_{GSS}	–	10	100	nA
Drain-source on-resistance V_{GS} = 0 V, I_D = 0.014 A	$R_{DS(on)}$	–	7.0	20	Ω
Dynamic Characteristics					
Forward transconductance $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$, I_D = 0.25 A	g_{fs}	0.14	0.2	–	S
Input capacitance V_{GS} = 0, V_{DS} = 25 V, f = 1 MHz	C_{iss}	–	110	150	pF
Output capacitance V_{GS} = 0, V_{DS} = 25 V, f = 1 MHz	C_{oss}	–	20	30	
Reverse transfer capacitance V_{GS} = 0, V_{DS} = 25 V, f = 1 MHz	C_{rss}	–	7	10	
Turn-on time t_{on}, ($t_{on} = t_{d(on)} + t_r$)	$t_{d(on)}$	–	4	6	ns
V_{DD} = 30 V, V_{GS} = – 2 V ... + 5 V, R_{GS} = 50 Ω, I_D = 0.25 A	t_r	–	10	15	
Turn-off time t_{off}, ($t_{off} = t_{d(off)} + t_f$)	$t_{d(off)}$	–	15	20	
V_{DD} = 30 V, V_{GS} = – 2 V ... + 5 V, R_{GS} = 50 Ω, I_D = 0.25 A	t_f	–	25	35	

Electrical Characteristics (cont'd)

at T_j = 25 °C, unless otherwise specified.

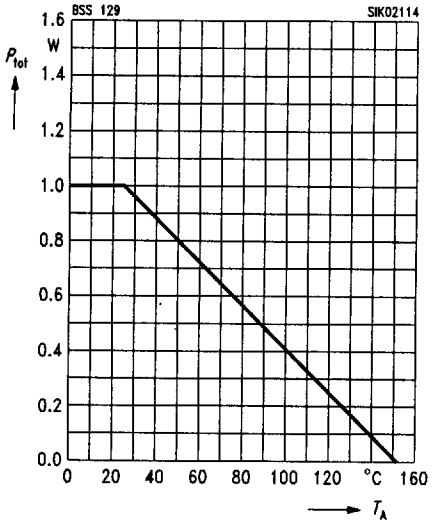
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse Diode					
Continuous reverse drain current T_A = 25 °C	I_S	–	–	0.15	A
Pulsed reverse drain current T_A = 25 °C	I_{SM}	–	–	0.45	
Diode forward on-voltage I_F = 0.3 A, V_{GS} = 0	V_{SD}	–	0.7	1.4	V

$V_{GS(th)}$ Grouping	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Range of $V_{GS(th)}$	$\Delta V_{GS(th)}$	–	0.2	V	–
Threshold Voltage selected in groups [1]:	$V_{GS(th)}$				V_{DS1} = 0.2 V;
F		– 1.600	– 1.400	V	V_{DS2} = 3 V;
G		– 1.700	– 1.500	V	I_D = 10 µA
A		– 1.800	– 1.600	V	
B		– 1.900	– 1.700	V	
C		– 2.000	– 1.800	V	
D		– 2.100	– 1.900	V	

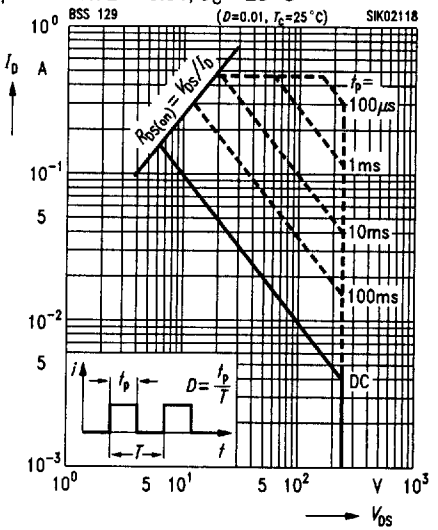
1) A specific group cannot be ordered seperately.
Each reel only contains transistors from one group.

Characteristics
at T_j = 25 °C, unless otherwise specified.

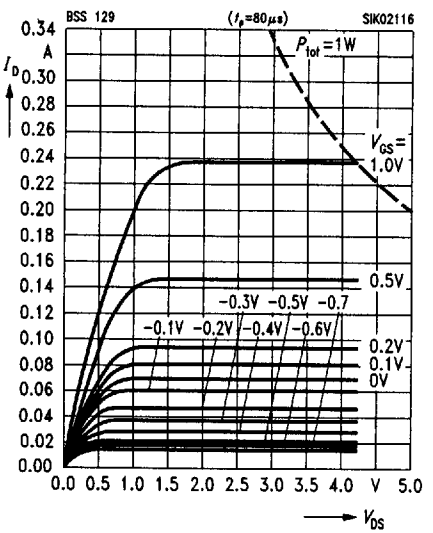
Total power dissipation $P_{tot} = f(T_A)$



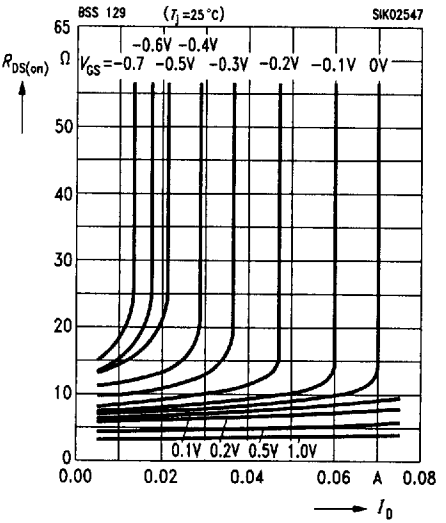
Safe operating area $I_D = f(V_{DS})$
parameter: D = 0.01, T_C = 25 °C



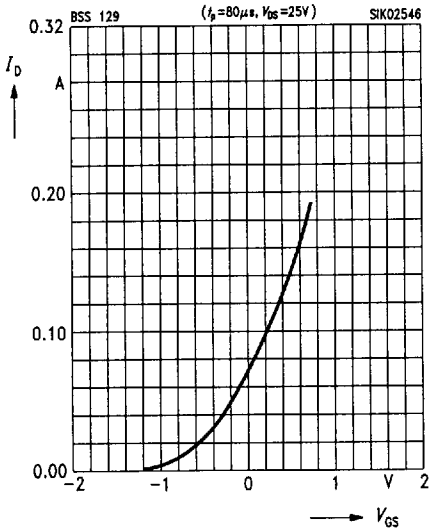
Typ. output characteristics $I_D = f(V_{DS})$
parameter: t_p = 80 µs



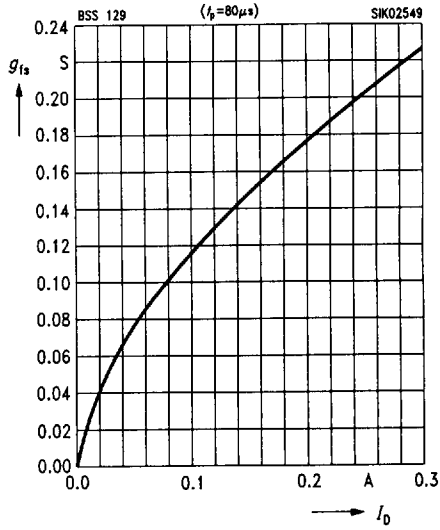
Typ. drain-source on-resistance
$R_{DS(on)} = f(I_D)$
parameter: V_{GS}



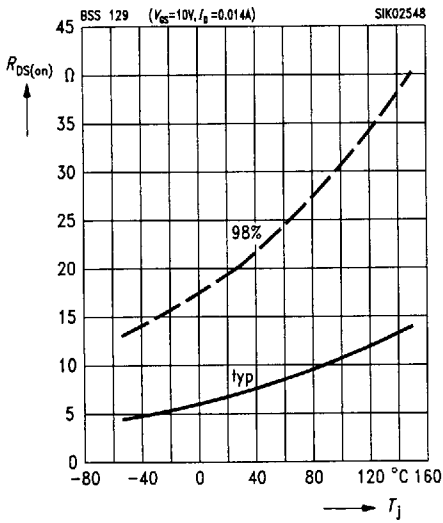
Typ. transfer characteristics $I_D = f(V_{GS})$
parameter: $t_p = 80\ \mu s$, $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$



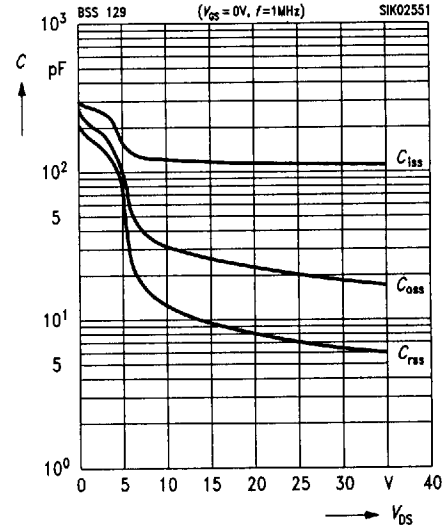
Typ. forward transconductance $g_{fs} = f(I_D)$
parameter: $V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$, $t_p = 80\ \mu s$



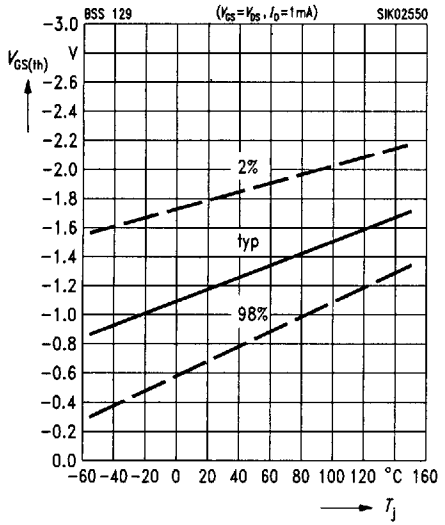
Drain-source on-resistance
$R_{DS(on)} = f(T_j)$
parameter: $I_D = 0.014$ A, $V_{GS} = 0$ V, (spread)



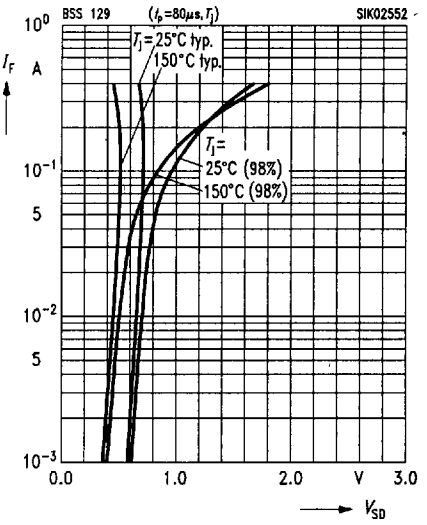
Typ. capacitances $C = f(V_{DS})$
parameter: $V_{GS} = 0, f = 1$ MHz



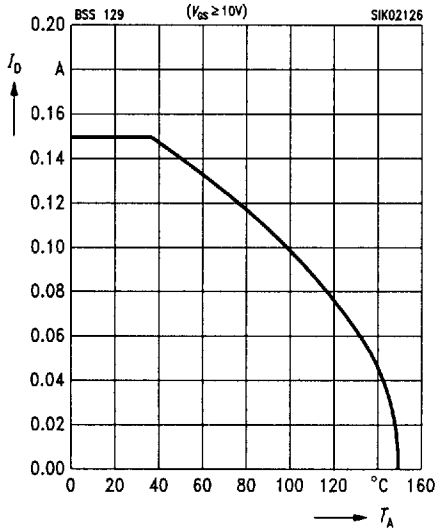
Gate threshold voltage $V_{GS(th)} = f(T_j)$
parameter: V_{DS} = 3 V, I_D = 1 mA, (spread)



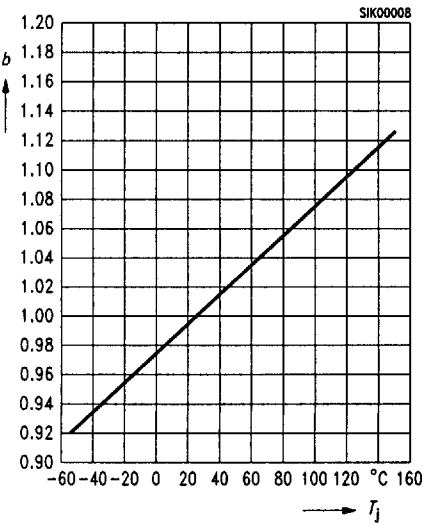
Forward characteristics of reverse diode
$I_F = f(V_{SD})$
parameter: t_p = 80 µs, T_j (spread)



Drain current $I_D = f(T_A)$
parameter: $V_{GS} \geq 3$ V



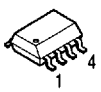
Drain-source breakdown voltage
$V_{(BR)\,DSS} = b \times V_{(BR)DSS}$ (25 °C)

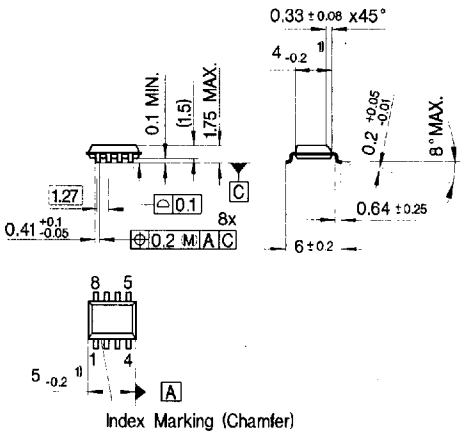


Gehäusemaßbilder
(Maße in mm, wenn nicht anders angegeben)

Package Outlines
(Dimensions in mm, unless otherwise specified)

P-DSO-8-6/-7
Gewicht etwa 0.15 g
Approx. weight 0.15 g

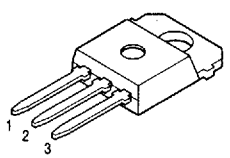


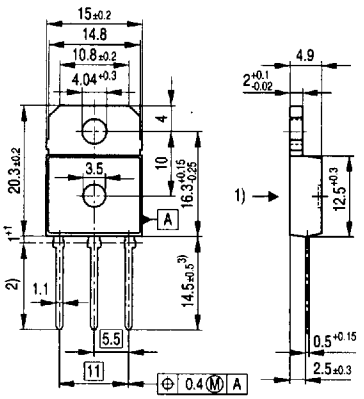


1) Does not include plastic or metal protrusion of 0.15 max. per side

Bild 16 **Figure 16**

P-TO218-AA (P-TO218-2-1)
Gewicht etwa 4.9 g
Approx. weight 4.9 g



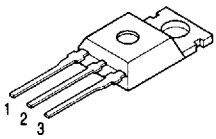


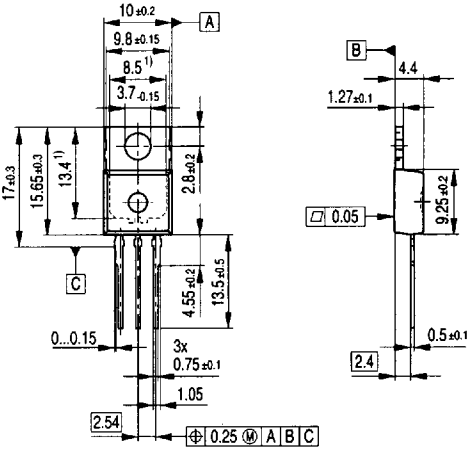
1) Punch direction, burr max. 0.04
2) Dip tinning
3) Max. 15.5 by dip tinning
press burr max. 0.05
radii not dimensioned max. 0.2

GPT05156

Bild 17 **Figure 17**

P-TO220-3-1
Gewicht etwa 1.8 g
Approx. weight 1.8 g

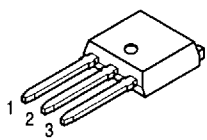


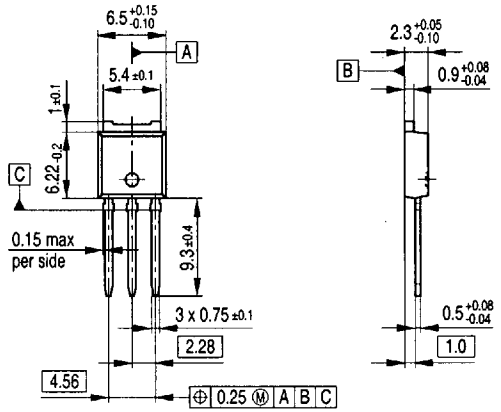


1) Typical
All metal surfaces tin plated, except area of cut. GPT05155

Bild 18 **Figure 18**

P-TO251-3-1
Gewicht etwa 2.0 g
Approx. weight 2.0 g

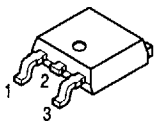


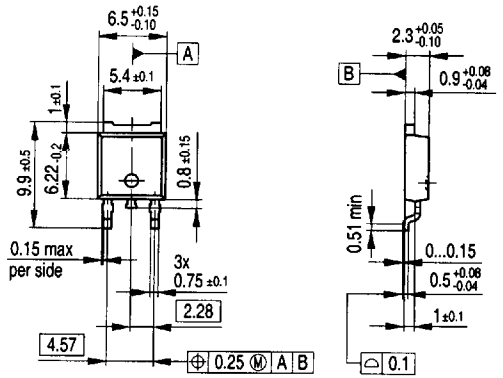


All metal surfaces tin plated, except area of cut. GPT09050

Bild 19 **Figure 19**

P-TO252-3-1
Gewicht etwa 0.38 g
Approx. weight 0.38 g



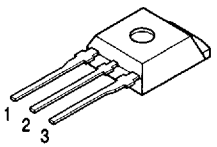


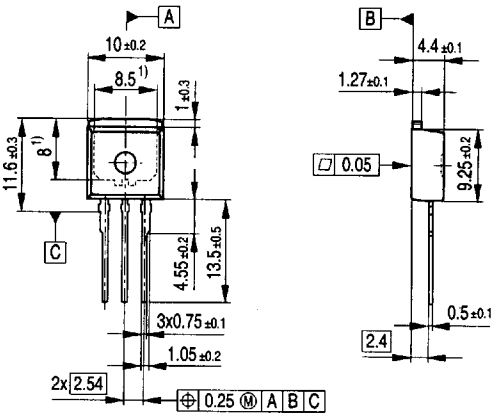
All metal surfaces tin plated, except area of cut.

GPT09051

Bild 20 **Figure 20**

P-TO262-3-1/I²PAK



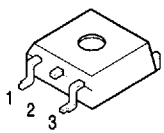


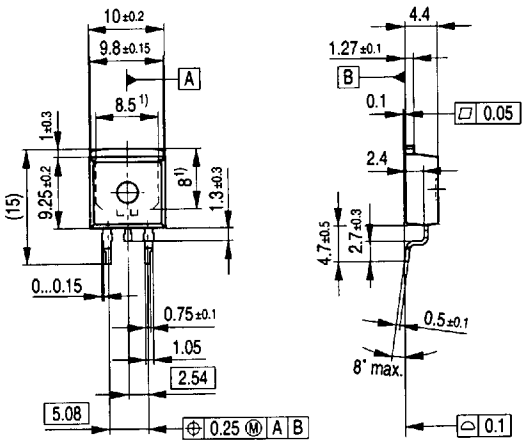
1) Typical
Metal surface min. X = 7.25, Y = 7.35
All metal surfaces tin plated, except area of cut.

GPT09244

Bild 21 **Figure 21**

P-TO263-3-2/D²PAK
Gewicht etwa 1.38 g
Approx. weight 1.38 g



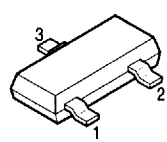


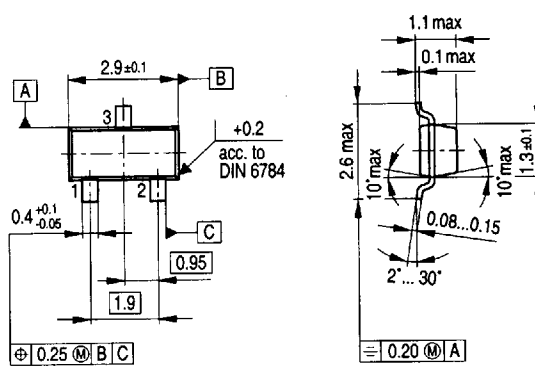
1) Typical
All metal surfaces tin plated, except area of cut.

GPT09085

Bild 22 **Figure 22**

SOT-23 (P-SOT23-3-1)
Gewicht etwa 0.01 g
Approx. weight 0.01 g

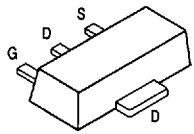




GPS05557

Bild 23 **Figure 23**

SOT-89
Gewicht etwa 0.01 g
Approx. weight 0.01 g



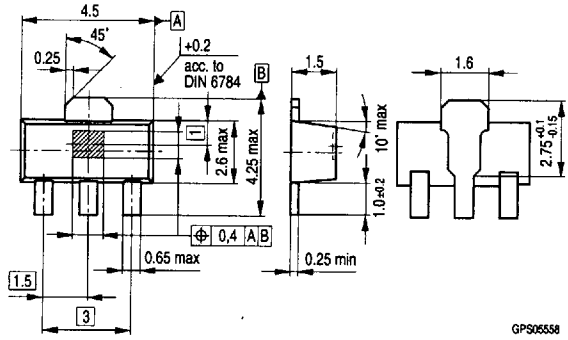
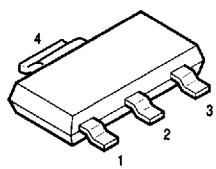


Bild 24 **Figure 24**

SOT-223 (P-SOT223-4-1)
Gewicht etwa 0.15 g
Approx. weight 0.15 g



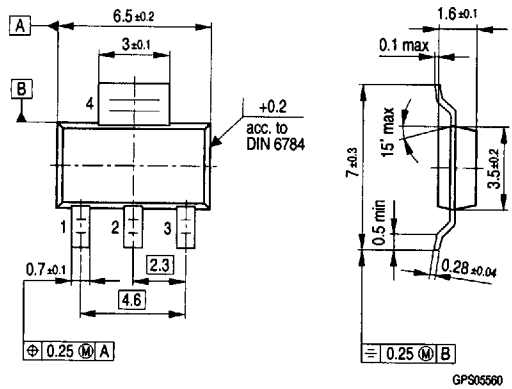
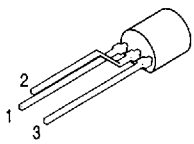


Bild 25 **Figure 25**

TO-92
Gewicht etwa 0.23 g
Approx. weight 0.23 g



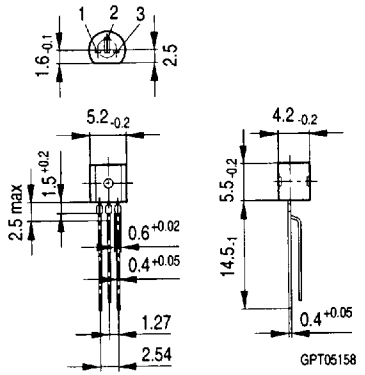
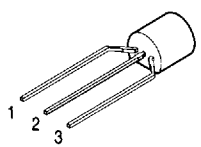


Bild 26 **Figure 26**

TO-92-E6288
Gewicht etwa 0.23 g
Approx. weight 0.23 g



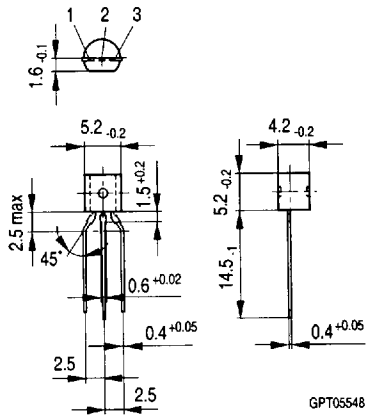


Bild 27 **Figure 27**

Sorts of Packing
Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

SMD = Surface Mounted Device